

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7329599

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	ZHONG YE	04/21/2022
	DANYANG ZHU	04/21/2022
	QIXIANG HAN	05/12/2022
RECEIVING PARTY DATA		
Name:	INVENTCHIP TECHNOLOGY CO., LTD.	
Street Address:	BUILDING 3-8F, NO. 99, OCEAN NO. 4 ROAD	
Internal Address:	NANHUI NEW CITY TOWN, PUDONG NEW DISTRICT	
City:	SHANGHAI	
State/Country:	CHINA	
Postal Code:	201306	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	17663286	
CORRESPONDENCE DATA		
Fax Number:	(972)732-9218	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	9727321001	
Email:	docketing@slatermatsil.com	
Correspondent Name:	SLATER MATSIL, LLP	
Address Line 1:	17950 PRESTON ROAD, SUITE 1000	
Address Line 4:	DALLAS, TEXAS 75252	
ATTORNEY DOCKET NUMBER:	IVC21-0001US01	
NAME OF SUBMITTER:	KAREN VERTZ	
SIGNATURE:	/Karen Vertz/	
DATE SIGNED:	05/13/2022	
Total Attachments: 2		
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source=IVC21-0001US01_Assignment#page2.tif		

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and



WHEREAS, InventChip Technology Co., Ltd. ("Assignee"), a corporation organized and existing under the laws of China, with its principal office at Building 3-8F, No. 99, Ocean No. 4 Road, Nanhui New City Town, Pudong New District, Shanghai, China 201306, is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Totem-Pole Bridgeless Power Factor Correction Device and Power Supply			
SIGNATURE OF INVENTOR AND NAME	 Zhong Ye	 Danyang Zhu	Qixiang Han	
DATE	Apr. 21, 2022	4/21/2022		
RESIDENCE	Plano, TX	Cary, NC	Shanghai, China	

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

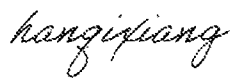
WHEREAS, InventChip Technology Co., Ltd. ("Assignee"), a corporation organized and existing under the laws of China, with its principal office at Building 3-8F, No. 99, Ocean No. 4 Road, Nanhui New City Town, Pudong New District, Shanghai, China 201306, is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Totem-Pole Bridgeless Power Factor Correction Device and Power Supply			
SIGNATURE OF INVENTOR AND NAME	Zhong Ye	Danyang Zhu	 Qixiang Han	
DATE			5/12/2022	
RESIDENCE	Plano, TX	Cary, NC	Shanghai, China	